

WHAT IS CLAIMED IS:

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1. A semiconductor assembly, comprising:
a leadframe;
a die coupled to the leadframe;
at least one channel formed in a top surface of the
leadframe; and
a mold compound for encapsulating the semiconductor
assembly wherein the mold compound flows into the at least one
channel and bonds with the at least one channel forming a lock
10 between the mold compound and the leadframe.

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2. The semiconductor assembly in accordance with Claim
1 further comprising:
a first raised area on the leadframe where the die is
coupled; and
a plurality of second raised areas on the leadframe used
for wirebonds wherein the plurality of second raised areas allow
the mold compound to get underneath the wirebonds and capture the
wirebonds.

3. The semiconductor assembly in accordance with Claim
1 further comprising a plurality of channels formed in the top
surface of the leadframe.

4. The semiconductor assembly in accordance with Claim 1 wherein the at least one channel is triangular in shape.

5. The semiconductor assembly in accordance with Claim 1 wherein the at least one channel is "U" shaped.

6. The semiconductor assembly in accordance with Claim 4 wherein the at least channel is formed by stamping and coining the leadframe.

7. The semiconductor assembly in accordance with Claim 5 wherein the at least channel is formed by etching the leadframe.

8. A mounting for a semiconductor package, comprising:
a leadframe; and

at least one channel formed in a top surface of the leadframe.

9. The mounting for a semiconductor package in accordance with Claim 8 wherein the at least one channel forms a lock between the leadframe and a mold compound which flows into the at least one channel.

10. The mounting for a semiconductor package in accordance with Claim 8 further comprising:

a first raised area on the leadframe forming a die pad;
and

5 a plurality of second raised areas on the leadframe used for wirebonds wherein the plurality of second raised areas allow a mold compound to get underneath the wirebonds and capture the wirebonds.

10 11. The mounting for a semiconductor package in accordance with Claim 8 further comprising a plurality of channels formed in the top surface of the leadframe.

15 12. The mounting for a semiconductor package in accordance with Claim 8 wherein the at least one channel is triangular in shape.

20 13. The mounting for a semiconductor package in accordance with Claim 8 wherein the at least one channel is "U" shaped.

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14. A mounting for a semiconductor package, comprising:
a leadframe; and

25 means formed on the leadframe for forming a lock between the leadframe and a mold compound which flows into the means.

15. The mounting for a semiconductor package in accordance with Claim 14 further comprising:

a raised area on the leadframe forming a die pad; and
means for allowing a mold compound to get underneath

5 wirebonds on the leadframe and capture the wirebonds.

16. A method for bonding a mold compound to a leadframe, comprising:

forming channels in a leadframe; and

10 depositing a molding compound on the leadframe wherein the molding compound will flow into the channels for bonding the mold compound to the leadframe.

15 17. The method of Claim 16 further comprising the step of forming triangular shaped channels.

18. The method of Claim 17 wherein the step of forming triangular shaped channels further comprises the steps of stamping the leadframe to form the channels.

20 19. The method of Claim 18 further comprising the step of coining the channels to flatten build-up around an opening of the channel caused by stamping the leadframe.

25 20. The method of Claim 16 further comprising the step of forming "U" shaped channels.

21. The method of Claim 20 further comprising the step of etching the leadframe to form the "U" shaped channels.

22. The method of Claim 16 further comprising the step of forming raised areas on the leadframe to be used for wirebonds wherein the raised areas allow a mold compound to get underneath the wirebonds and capture the wirebonds.

23. The method of Claim 16 wherein the step of forming raised areas further comprises the step of etching the leadframe to form the raised areas.

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